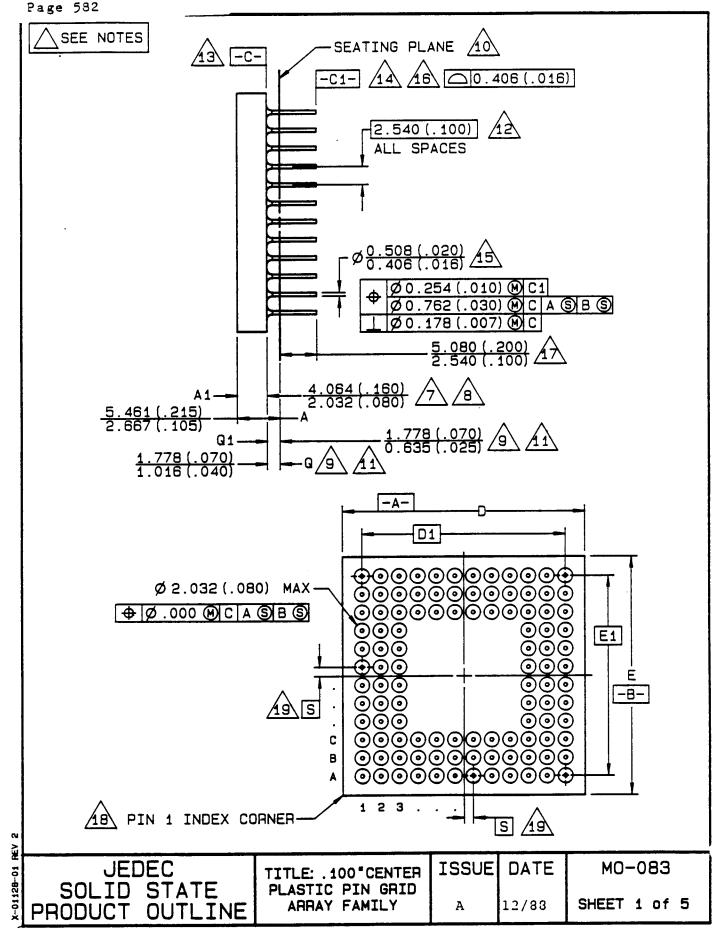
MO-083

.100" CENTER

PLASTIC

PIN GRID ARRAY FAMILY



S Y.					VAR]	[AT	ZNDI	(DIME	NSIONS I	N INCHES	3)
M B		AA	N D		AB	N		AC	N		AD	Z []
a L	MIN.	MAX.	E	MIN.	MAX.	Ŧ	MIN.	MAX.	T E	MIN.	MAX.	Ī
D	.940	.980	20	1.040	1.080	20	1.140	1.180	20	1.240	1.280	20
D1	.800	BSC		.900	BSC		1.000	BSC		1.100	BSC	
Ε	,940	.980	20	1.040	1.080	20	1.140	1.180	20	1.240	1.280	20
E1	.800	BSC		.900 BSC			1.000 BSC			1.100 BSC		
М	. 9		4			4		l	4			4
N		81	5		100	5	·	121	5		144	5
S	.000	BSC	19	.050	BSC	19	.000	BSC	19	.050	BSC	19
NOTE	1, 2, 3	3, 6, 9, 18		1, 2, :	3, 6, 9, 18	1	1, 2, 3	3, 6, 9, 18		1, 2,	3, 6, 9, 18	
	·	AE	N		AF	ם		AG	N		AH	2 🗆
	MIN.	MAX.	T E	MIN.	MAX.	E	MIN.	MAX.	T E	MIN.	MAX.	T E
D	1.340	1.380	50	1.440	1.480	20	1.540	1.580	20	1.640	1.680	20
D1	1.200	BSC		1.300	BSC		1.400	BSC		1.500	BSC	
Ε	1.340	1.380	20	1.440	1.480	20	1.540	1.580	20	1.640	1.680	20
E1	1.200	BSC		1.300	BSC		1.400	BSC		1.500	BSC	
М	13		4	14 4		4	15		4			4
N		169	5		196	5		225	5		256	5
S	.000 BSC 19		19	.050 BSC 19		19			19			19
NOTE	1, 2, 3, 6, 9, 18		1, 2, 3, 6, 9, 18		1, 2, 3, 6, 9, 18		ļ	1, 2, 3, 6, 9, 18				
	LA		םא	1		ם		AL.			AM	N
	MIN.	MAX.	Ε	MIN,	MAX.	E	MIN.	MAX.	T E	MIN.	MAX.	T E
ם	1.740	1.780	20	1.840	1.880	20	1.940	1.980	20	2.040	2.080	20
D1	1.600	BSC		1.700	B2C.		1.800	BSC		1. 9 00	BSC	
Ε	1.740	1.780	20	1.840	1.880	20	1.940	1.980	20	2.040	2.080	20
E1	1.600 BSC			1.700 BSC			1.800 BSC			1.900 BSC		
М	17		4	1 -		4	19		4	2		4
N		289	5		324	5		361	5		400	5
S	.000	BSC	19	.050	BSC	19	.000	BSC	19	.050	BSC	19
NOTE	12	3, 6, 9, 18	1, 2, 3, 6, 9, 18									
REF.: ITEM 11243												
ISSUE:												
1	JEDEC				TITLE: .100" CENTER			R ISSUE DA		MO-083		
1	SOLID STATE				PLASTIC PIN GRID			12/00		1		
PRODUCT OUTLINE ARRAY FAMILY A 12/88 SHEET 2 of 5												

					\	T A T	TONS	CDIMEN	ISTON	IS IN MI	LIMETER	(2)
S Y M	·	VARIATIONS (DIMENSIONS IN MILLIMETERS)										
В		AA	ום צ		AB	ָר - ב		AC	N		AD	-
L		MAX.	Ē	MIN.	MAX.	Ė	MIN.		Ė		MAX.	E
D		24.89	20		27.43	20		29.97	1	ſ	32.51	20
D1	20.32				BSC			BSC	1	27.94		
	23.88		50	26.42	•	50		•	50		•	20
E1	20.32			22.86 BSC			25.40 BSC			27.94 BSC		
М	9		4	10		4	11		4	1	2	4
N			5		100	5	·	•	5	1	144	5
2		320	19		BSC					1.27	-	19
NOTE	1, 2, 3	3, 6, 9, 18		12	3, 6, 9, 18	1	123	3, 6, 9, 18		ı, z,	3, 6, 9, 18	
l ,												
		AE	םצ		AF	וא		AG	ם א		AH	7 D Z
	MIN.	MAX.	T E	MIN.	MAX.	T E	MIN.	MAX.	T E	MIN.	MAX.	T E
D	34.04	35.05	20	36.58	37.59	20	39.12	40.13	20	41.66	42.67	50
D1	30.48	BSC		33.02	BSC			BSC		38.10	BSC	
Ε	34.04	35.05	20	36.58	37.59	20	39.12	40.13	20	41.66	42.67	20
E1	30.48	BSC		33.02	BZC		35.56	BSC		38.10	BSC	
М	13		4	· .		4	i .		4			4
N			5		196	5		225	5		256	5
S			19			19				9 1.27 BSC		19
NOTE	1, 2, 3, 6, 9, 18			1, 2, 3, 6, 9, 18		1	1, 2, 3, 6, 9, 18		1, 2, 3, 6, 9, 18			
l .												
	LA		N	AK		מ	AL		םא	АМ		N
	MIN.	MAX.	E	MIN.	MAX.	T E	MIN.	MAX.	E	MIN.	MAX.	T E
ם	44.20	45.21	20	46.74	47.75	20	49.28	50.29	20	51.82	52.83	20
D1	40.64	BZC		43.18	BSC		45.72	BCC		38.10		
Ε	44.20	45.21	20	46.74	47.75	20	49.28	50.29	20	51.82	52.83	20
E1	40.64	BSC			BSC			BZC		38.10		
М	17		4	18		4	19		4	2		4
N		289	5		324	5		361	5		400	5
S	.00 I	BSC	19	1,27	BSC	19	.00		19	1.27	BSC	19
NOTE												
REF. ITEM 11-243												
ISSUE:												
	JEDEC				. TITLE: 2.54 mm			ISSUE DATE		M0-083		
1	SOLID STATE				CENTER PLASTIC PIN			N		1		
PRODUCT OUTLINE GRID ARRAY FAMILY A 12/88 SHEET 3 of 5												

NOTES:

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982
- 2. REFER TO APPLICABLE SYMBOL LIST
- 3. TERMINAL POSITION DESIGNATION PER JEDEC PUBLICATION 95, SECTION 2.2-5.
- 4. SYMBOL 'M' REPRESENTS THE PGA PIN MATRIX SIZE.
- 5. SYMBOL 'N' REPRESENTS THE MAXIMUM POSSIBLE NUMBER OF PINS.
- 6. 11 X 11 AND 12 X 12 MATRIX SIZES ARE SHOWN FOR ILLUSTRATION PURPOSES ONLY.
- DIMENSIONS A & A1 INCLUDE BOTH THE PACKAGE BODY AND THE LID FOR EITHER CAVITY-UP OR CAVITY-DOWN CONFIGURATION. (SEE SHT 5)
- DIMENSIONS A & A1 DO NOT INCLUDE HEATSINK OR OTHER ATTACHED FEATURES.
- STAND-OFFS ARE OPTIONAL, BUT SHOULD BE LOCATED ON THE PIN MATRIX DIAGONALS WHEN PRESENT.
- SEATING PLANE IS DEFINED BY STAND-OFFS WHEN PRESENT.
- DIMENSION Q APPLIES TO CAVITY-UP CONFIGURATION ONLY. DIMENSION Q1 APPLIES TO CAVITY-DOWN CONFIGURATION ONLY. (SEE SHT 5)
- ALL PINS ARE REQUIRED TO BE ON 2.540 (.100) GRID SPACING
- 13 -C- REFERENCE PLANE IS THE PLANE OF PIN TO PACKAGE INTERFACE.
- 14 -C1- IS THE PLANE OF PIN TIPS.
- 15 PIN DIAMETER EXCLUDES SOLDER DIP OR OTHER CUSTOM FINISHES.
- 16 PIN TIPS MAY HAVE A RADIUS OR CHAMFER.
- PIN GRID ARRAY PACKAGES WHICH ARE TO BE USED IN SOCKETS MAY REQUIRE A MINIMUM INSERTABLE PIN LENGTH OF 3.175 (.125).
- THERE MUST BE SOME TYPE OF A CORNER IDENTIFICATION ON BOTH TOP AND BOTTOM SURFACES OF THE PACKAGES. IDENTIFICATION TYPE IS OPTIONAL AND MAY CONSIST OF NOTCHES, CHAMFER, ID PINS, METALLIZATION OR OTHER FEATURE. FEATURES ON BOTH SURFACES ARE NOT REQUIRED TO BE IDENTICAL.
- S IS MEASURED WITH RESPECT TO -A- AND -B-
- 20. CONTROLLING DIMENSION: INCH

JEDEC	TITLE: .100 CENTER	ISSUE DATE		MO-083		
SOLID STATE	PLASTIC PIN GRID		i	SHEET 4 of 5		

